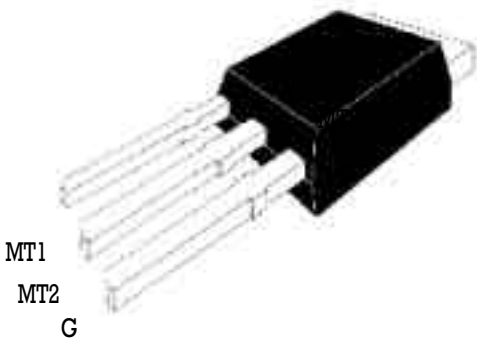


LOGIC LEVEL TRIAC

IPAK (Plastic)	On-State Current 8 Amp	Gate Trigger Current < 5 mA to < 10 mA
	Off-State Voltage 200 V ÷ 600 V	
	This series of TRIAC s uses a high performance PNP technology. These devices are intended for AC control applications using surface mount technology. The high commutation performances combined with high sensitivity, make them perfect in all applications like solid state relays, home appliances, power tools, small motor drives...	

Absolute Maximum Ratings, according to IEC publication No. 134

SYMBOL	PARAMETER	CONDITIONS	Min.	Max.	Unit
$I_{T(RMS)}$	RMS On-state Current	All Conduction Angle, $T_C = 110\text{ }^\circ\text{C}$	8		A
I_{TSM}	Non-repetitive On-State Current	Half Cycle, 60 Hz	84		A
I_{TSM}	Non-repetitive On-State Current	Half Cycle, 50 Hz	80		A
I^2t	Fusing Current	$t_p = 10\text{ ms}$, Half Cycle	36		A ² s
I_{GM}	Peak Gate Current	20 μs max.		4	A
P_{GM}	Peak Gate Dissipation	20 μs max.		10	W
$P_{G(AV)}$	Gate Dissipation	20 ms max.		1	W
di/dt	Critical rate of rise of on-state current	$I_G = 2 \times I_{GT}$ $T_r = 100\text{ ns}$, $F = 120\text{ Hz}$ $T_j = 125\text{ }^\circ\text{C}$	20		A/ μs
T_j	Operating Temperature Range		-40	+125	$^\circ\text{C}$
T_{stg}	Storage Temperature Range		-40	+150	$^\circ\text{C}$
T_L	Lead Temperature for soldering	10s max.		260	$^\circ\text{C}$

SYMBOL	PARAMETER	VOLTAGE			Unit
		B	D	M	
V_{DRM} V_{RRM}	Repetitive Peak Off State Voltage	200	400	600	V

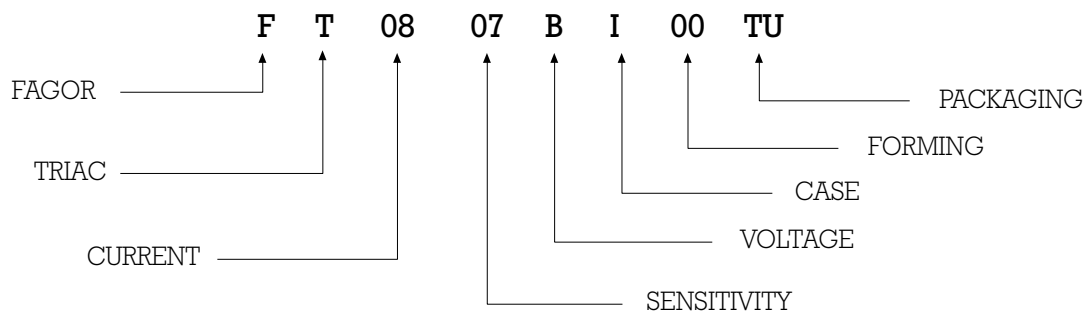
LOGIC LEVEL TRIAC

Electrical Characteristics

SYMBOL	PARAMETER	CONDITIONS	Quadrant		SENSITIVITY		Unit
					07	08	
I_{GT}	Gate Trigger Current	$V_D = 12 V_{DC}$, $R_L = 33$ $T_j = 25^\circ C$	Q1÷Q3 Q4	MAX	5 7	10	mA
I_{DRM} / I_{RRM}	Off-State Leakage Current	$V_R = V_{DRM}$, $V_R = V_{RRM}$,		MAX	1		mA
				MAX	5		μA
V_{TM}	On-state Voltage	$I_T = 11 \text{ Amp}$, $t_p = 380 \mu s$, $T_j = 25^\circ C$		MAX	1.55		V
V_{GT}	Gate Trigger Voltage	$V_D = 12 V_{DC}$, $R_L = 33$, $T_j = 25^\circ C$	Q1÷Q3	MAX	1.3		V
V_{GD}	Gate Non Trigger Voltage	$V_D = V_{DRM}$, $R_L = 3.3K$, $T_j = 125^\circ C$	Q1÷Q3	MIN	0.2		V
I_H^*	Holding Current	$I_T = 100 \text{ mA}$, Gate open, $T_j = 25^\circ C$		MAX	10	15	mA
I_L	Latching Current	$I_G = 1.2 I_{GT}$, $T_j = 25^\circ C$	Q1,Q3	MAX	10	20	mA
			Q2	MAX	15	30	
dv / dt^*	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}$, Gate open $T_j = 125^\circ C$		MIN	20	100	V/ μs
$(di/dt)_c^*$	Critical Rate of Current Rise	$(dv/dt)_c = 0.1 \text{ V}/\mu s$ $(dv/dt)_c = 15 \text{ V}/\mu s$ without snubber		MIN	3.5	5.4	A/ms
				MIN	1.8	2.8	
				MIN			
$R_{th(j-c)}$	Thermal Resistance Junction-Case				1.6		$^\circ C/W$
$R_{th(j-a)}$	Thermal Resistance Junction-Ambient				100		$^\circ C/W$

(*) For either polarity of electrode MT2 voltage with reference to electrode MT1.

PART NUMBER INFORMATION



LOGIC LEVEL TRIAC

Fig. 1: Maximum power dissipation versus average on-state current

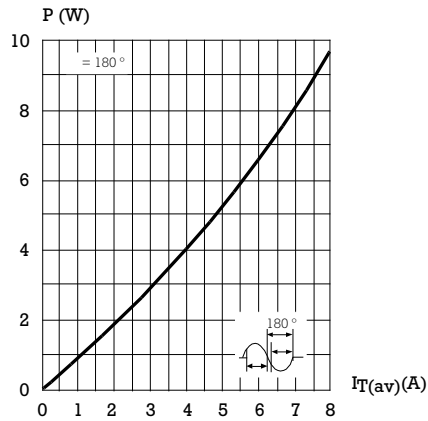


Fig. 2: Average and DC on-state current versus case temperature

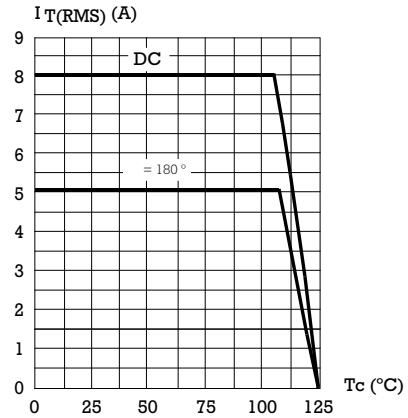


Fig. 3: Relative variation of thermal impedance junction to case versus pulse duration

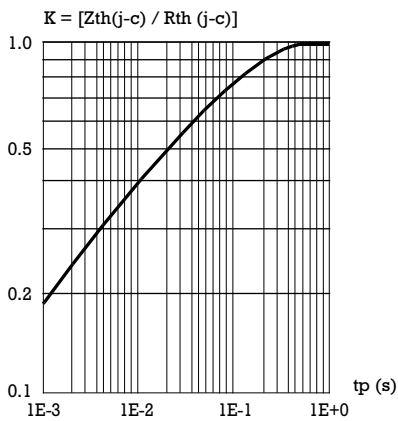


Fig. 4: Relative variation of gate trigger current and holding current versus junction temperature

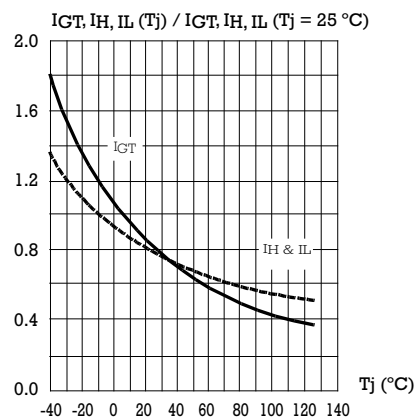


Fig. 5: Non repetitive surge peak on-state current versus number of cycles

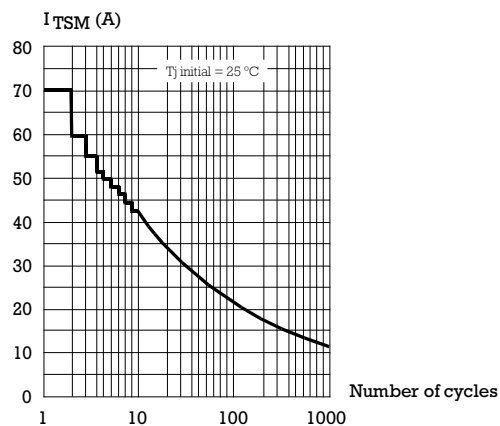
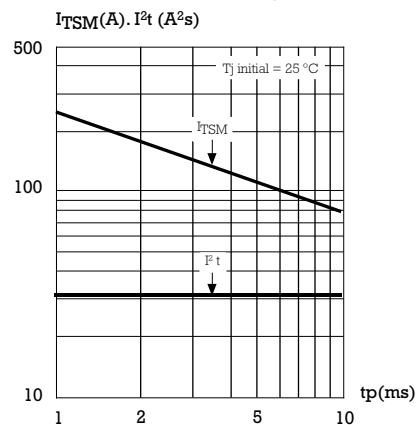
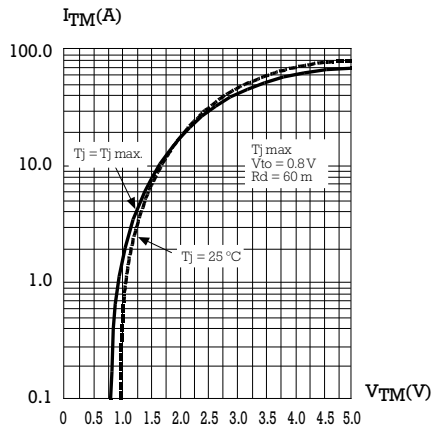


Fig. 6: Non repetitive surge peak on-state current for a sinusoidal pulse with width: tp < 10 ms, and corresponding value of I²t.



LOGIC LEVEL TRIAC

Fig. 8: On-state characteristics (maximum values).



PACKAGE MECHANICAL DATA IPAK TO 251-AA

REF.	DIMENSIONS		
	Millimeters		
	Min.	Nominal	Max.
A	2.19	2.3±0.08	2.38
A1	0.89	1.067±0.01	1.14
b	0.64	0.75±0.1	0.89
b1	0.76	0.95	1.14
c	0.46		0.58
c2		0.8±0.013	
D	5.97	6.1±0.1	6.22
D1	5.21		5.52
E	6.35	6.58±0.14	6.73
E1	5.21	5.36±0.1	5.46
e		2.28BSC	
L	8.89	9.2±0.2	9.65
L1	1.91	2±0.1	2.28
L3	0.89		1.27

Marking: type number
Weight: 0.2 g